Title: IMPROVED INTEGRATED CIRCUIT BURN-IN SYSTEMS (as amended)

Assignee: Intel Corporation

## IN THE SPECIFICATION

Please make the paragraph substitutions indicated below. The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs.

The paragraph beginning on page 1, line 18 is amended as follows:

It is well known to perform accelerated life testing on ICs to ensure that the ICs do not prematurely fail when they have been incorporated into higher levels of electronic packaging, such as [[a]] computer systems, (e.g., desktop, laptop, hand-held, server, etc.), wireless communications devices (e.g., cellular phones, cordless phones, pagers, etc.), computer-related peripherals (e.g., printers, scanners, monitors, etc.), entertainment devices (e.g., televisions, radios, stereos, tape and compact disc players, video cassette recorders, MP3 (Motion Picture Experts Group, Audio Layer 3) players, etc.), and the like.

The paragraph beginning on page 6, line 28 is amended as follows:

Thus, while burn-in test <u>fixtures 150</u> [[fixtures150]] are inside burn-in oven 200, they are functionally connected to burn-in system 1 (FIG. 1) via a network of connectors and wires (not shown) in order to operate the ICs on test fixtures 150 at elevated operating voltage and to toggle as many circuit nodes as possible on the ICs. Burn-in oven 200 can also include power and clock circuits (not shown) to provide power and clock signals to the ICs undergoing burn-in.

The paragraph beginning on page 7, line 28 is amended as follows:

In 514, a determination is made whether the temperature indication matches the new stored temperature value. If so, the method goes to 516; otherwise other wise, it returns to 512.